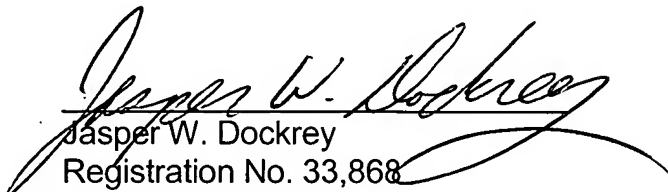


## REMARKS

The applicants respectfully request entry of the amendment prior to commencing examination of the application.

Respectfully submitted,

  
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## Amended Abstract

The invention concerns a method of making a complex microelectronic structure by assembling two substrates (~~5, 6; 11, 13~~) through two respective linking surfaces, the structure being designed to be dissociated at a separation zone. The invention is characterized in that it consists, prior to ~~assembling~~ assembly, in producing a state difference ~~of state of~~ in the tangential stresses between the two surfaces to be assembled, ~~said the state~~ the state difference being selected so as to ~~obtain~~ produce in the assembled structure a predetermined stress state ~~of stresses~~ at the time of dissociation.